

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1	INITIAL RELEASE	27/03/19	RAJA
2	ALPHA RELEASE	13/05/19	RAJA
3	ALPHA RELEASE	31/05/19	RAJA
5	BETA RELEASE	05/02/20	GGAN

NOTES: (UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED.
2. MATERIAL:

A. FR4 OR EQUIVALENT MATERIAL(HIGH ELECTRONIC RELIABILITY) MUST CONFIRM TO UL94V-0

B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM.

C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION.
3. DRILLING:

A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/- .003 tol.

UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.

B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:

COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:

A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.

B. FABRICATOR TO PLACE DATE CODE, LOGO AND RoHS COMPILANT SYMBOL IN SILKSCREEN ON SECONDARY SIDE.
6. FINAL FABRICATION:

A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR *BLUE**
7. FINISH:

A. SHALL BE ELECTROLESS NIKEL / IMMERSION GOLD(ENIG).

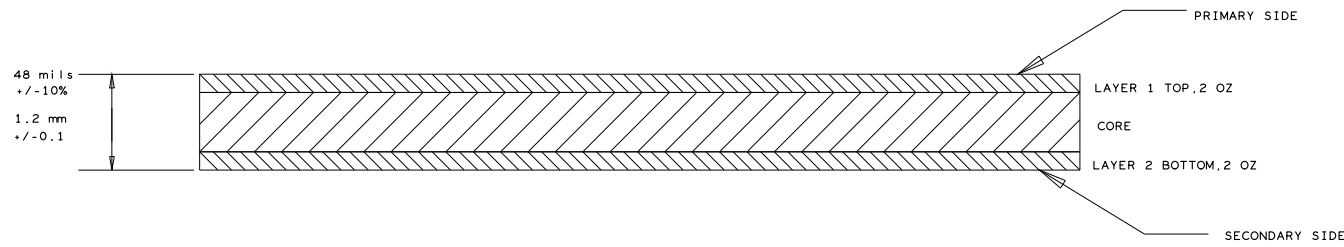
B. NICKEL THICKNESS: 100-200 MICROINCHES.

C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY. FLAMABILITY RATING (94-V0).
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .007 in/in.
11. TESTING:

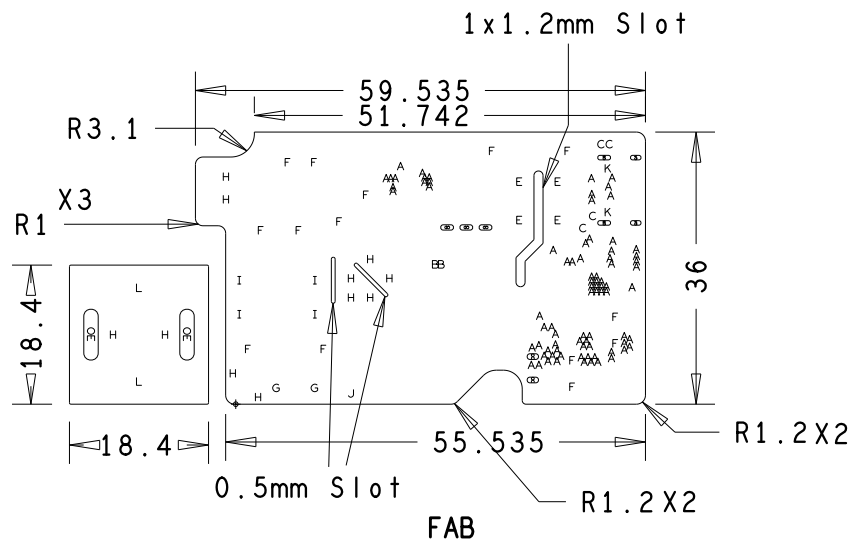
A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.

B. T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.
12. ENSURE ALL THE VIA HOLES ARE FILLED WITH SOLDER MASK TO ENSURE GOOD QUALITY OF SILK SCREEN PRINT.
13. CARE MUST BE TAKEN TO AVOID OVER ETCHING OF COPPER ON PADS.
14. THIS IS HIGH VOLTAGE BOARD. SO DON'T ADD THIEVING COPPER IN VOID AREA FOR COPPER BALANCE.
15. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH CTI STANDARD OF 400<CTI<600


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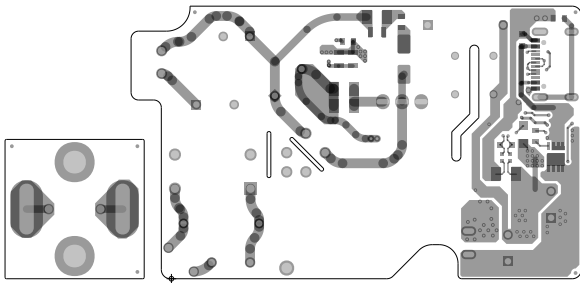


SHOULD PROVIDE PANEL HANDLING AREA FOR MACHINE ASSEMBLY.

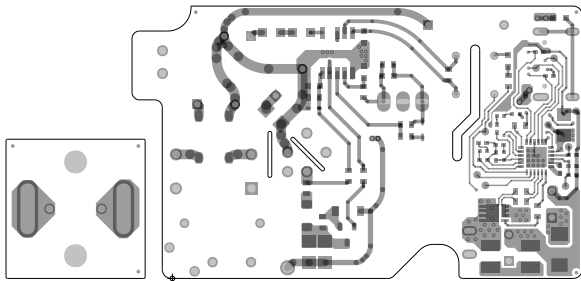


DRILL CHART: TOP & BOTTOM				
ALL UNITS ARE IN MILLIMETERS				
FIGURE	FINISHED SIZE	TOLERANCE, DRILL	PLATED	QTY
A	0.254	+0.0762/-0.0762	PLATED	81
B	0.381	+0.0762/-0.0762	PLATED	2
C	0.508	+0.0762/-0.0762	PLATED	4
E	0.8	+0.076/-0.076	PLATED	4
F	0.85	+0.0762/-0.0762	PLATED	14
G	0.92	+0.0762/-0.0762	PLATED	2
H	1.02	+0.0762/-0.0762	PLATED	11
I	1.1	+0.0762/-0.0762	PLATED	4
J	1.4	+0.0762/-0.0762	PLATED	1
K	0.65	+0.0508/-0.0508 NON-PLATED		2
L	3.0	+0.0508/-0.0508 NON-PLATED		2
Ø	1.4x0.5999	+0.0762/-0.0762	PLATED	2
Ø	1.5x0.75	+0.0762/-0.0762	PLATED	2
Ø	1.7x0.5999	+0.0762/-0.0762	PLATED	2
Ø	1.7x0.7	+0.0762/-0.0762	PLATED	3
Ø	6.731x1.905	+0.0762/-0.0762	PLATED	2

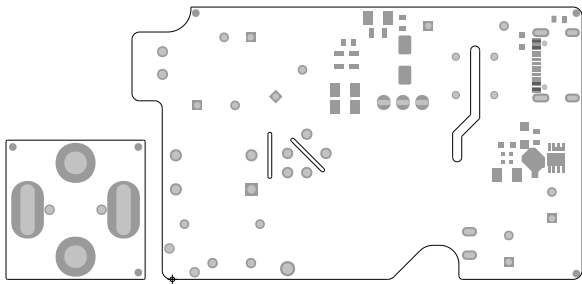
UNLESS OTHERWISE SPECIFIED		SIGNATURES	DATE	<div>198 CHAMPION COURT SAN JOSE, CA 95134 (408) 943-2600</div>	
DIMENSIONS ARE IN INCHES		DRAWN : HUSA	05/02/20		
TOLERANCES ON: ANGLES +/- 2°		CHECKED : PVV/RAAH	05/02/20		
2 PL DECIMALS +/- .010		ENGRG : GGAN	05/02/20		
3 PL DECIMALS +/- .005		ISSUED		FABRICATION DRAWING PAG1S+PAG1P 33W SOLUTION DEMO BOARD	
THIRD ANGLE PROJECTIONS				SIZE C	REV 05
CYPRESS PROPRIETARY				FSCM NO	DWG NO 610-XXXXXX-XX
THIS DOUCUMENT CONTAINS CONFIDENTIAL, PROPRIETARY INFORMATION THAT IS CYPRESS SEMICONDUCTOR PROPERTY. DO NOT DISCLOSE TO OR DUPLICATE FOR OTHERS EXCEPT AS AUTHORIZED BY CYPRESS.				SCALE: 1/1	SHEET: 1 OF 1



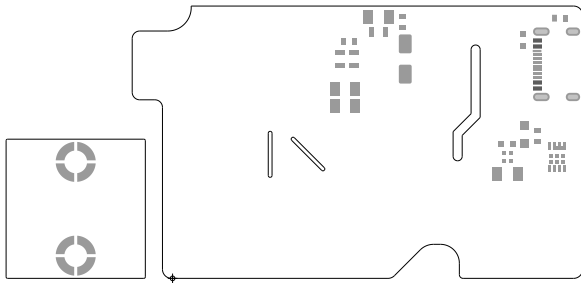
600-XXXXX-XX REV05 PRIMARY SIDE



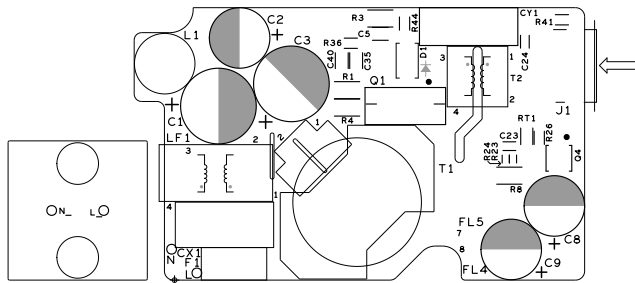
000-XXXXX-XX REV02 SECONDARY SIDE



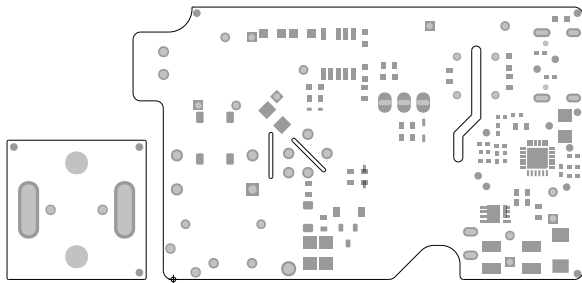
600-XXXXX-XX REV05 SOLDER MASK PRIMARY SIDE



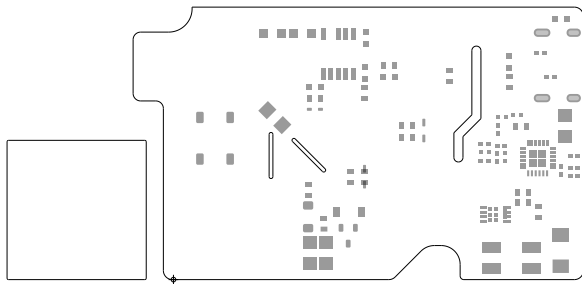
600-XXXXX-XX REV05 PRIMARY SOLDERPASTE



600-XXXXX-XX REV05 PRIMARY SILKSCREEN



600-XXXX-XX REV02 SECONDARY SOLDER MASK



600-XXXX-XX REV02 SECONDARY SOLDERPASTE

600-XXXX-XX REV05 SECONDARY SILKSCREEN

